

MECHANICAL CASE OUTLINE

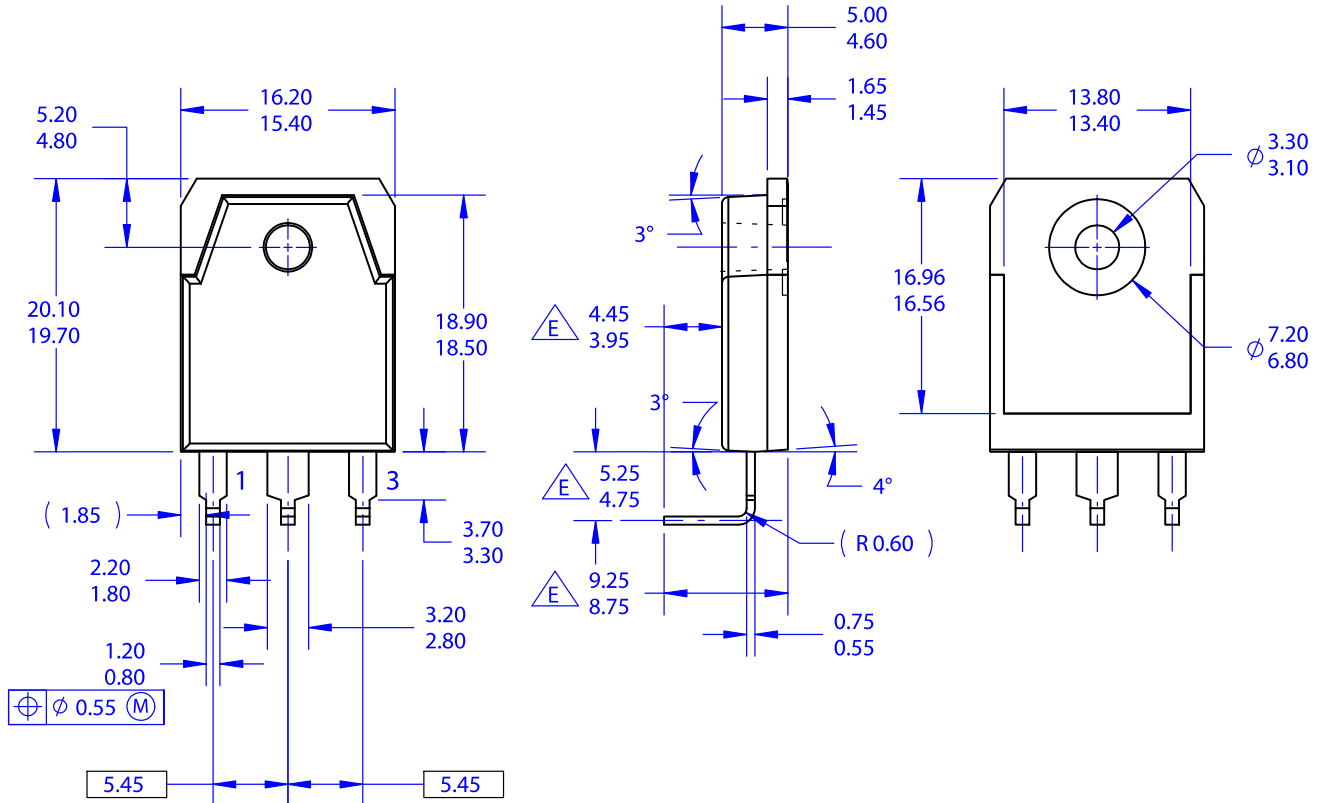
PACKAGE DIMENSIONS

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TO-3P-3LD LEADFORM CASE 340BR ISSUE O

DATE 31 OCT 2016



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE REFERENCE EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

E DOES NOT COMPLY EIAJ SC-65.

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DESCRIPTION:	TO-3P-3LD LEADFORM	PAGE 1 OF 1

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